

200mm Semi-Automatic UV Irradiation System

RAD-2000m/8



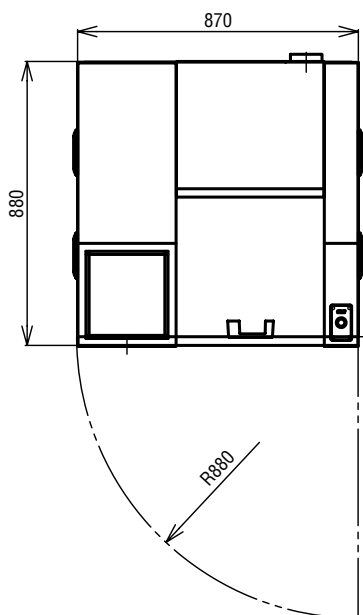
Outline

- Semi-automatic UV irradiation system used for curing UV type dicing tape.
- Applicable for ring frame sizes used for 150mm and 200mm wafers.

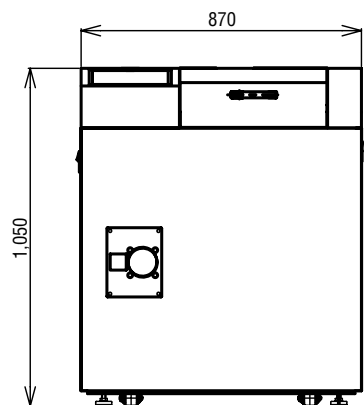
Suitable Tapes

- Dicing tape : Adwill D series
- Dicing die bonding tape : Adwill LE Tape

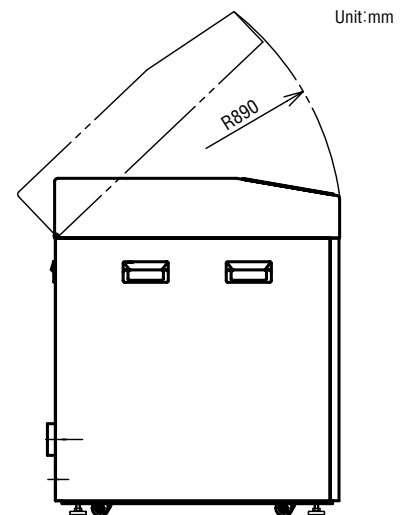
External View



Top View



Front View



Left Side View

Unit:mm

Facility

Power Supply	Voltage	: AC200-230V ±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: single phase
	Capacity	: 4.0kW
Air Supply	Air pressure	: 0.5-0.8MPa
	Air consumption	: >10L/min (ANR)
Nitrogen Source	Nitrogen pressure	: 0.29MPa
	Nitrogen consumption	: >30L/min (ANR)

Applicable Wafer Size 150mm, 200mm

Size

Width : 870mm
Depth : 880mm
Height : 1,050mm

Weight 400kg

Processing Capacity within 15sec/wafer (excludes setting time)

The above processing capacity is based on following conditions:

Wafer : 200mm diameter non-polished mirror wafer
Ring frame : for 200mm wafer